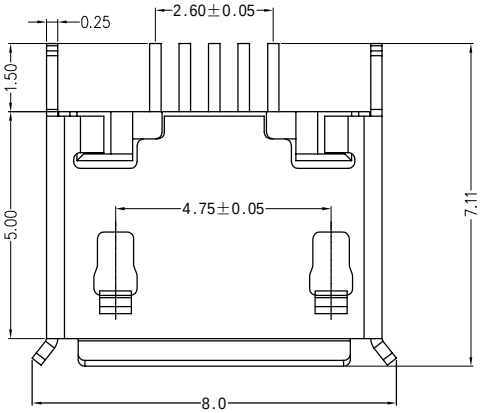
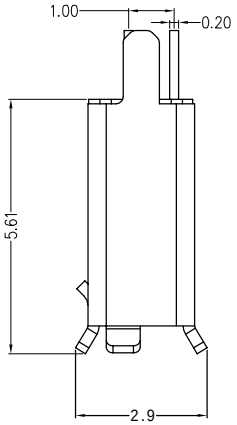
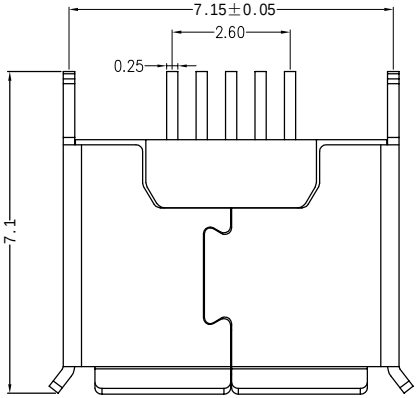
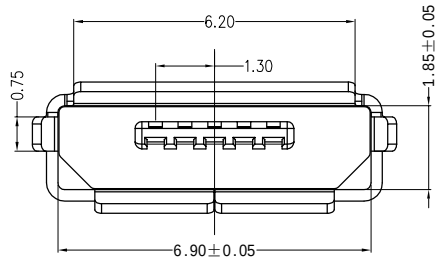
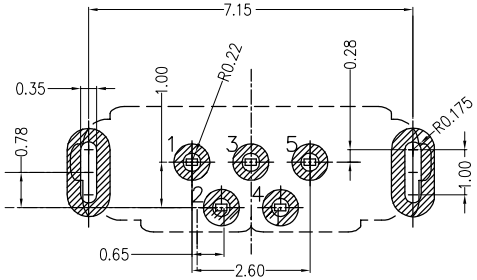
REV.	ECN NO	LOCATIONS	DESCRIPTION	DATE











RECOMMEDED P C B LAYOUT

Note:

1.Material:

1.1 Housing: High temperature thermoplastic with g.f,UL94v-0

1.2 Contact: copper alloy,t=0.2mm

1.3 Shell: SUS201,t=0.25mm

2.Specification:

2.1 Current rating: 1 A Max.

2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.

2.3 Contact resistance: 30 MΩ Max.

2.4 Insulation resistance: 100 MΩ Min.

2.5 Total mating force: 3.57 Kgf Max.

2.6 Total unmating force: 1.0 Kgf Min

2.7 Temperature range: -30℃~80℃

外壳材质

c:SUS201

外壳电镀

1:N50u''

2:雾T50u''

3:N+Au1u''(脚)

4:Au1u''

端子电镀 01:Au1u'';02:Au1.5u'';03:Au3u''
05:Au5u'' ;10:Au10u'';15:Au15u'';30:Au30u''

主体颜色 B:黑色

主体材质 1:LCP

端子材质 4:C5191R-EH

PART NO: USB-F06505-LC017		MATERAL: SEE NOTE	WFD CONN 深圳市旺富达电子有限公司 SHEN ZHEN WFD ELECTRONICS CO., LTD
MODEL NO: XX		FINSH: SEE NOTE	TITLE: MICRO 5P/F AB TYPE 180插板脚长1.5
UNIT: MM	SIZE: A4	COLOR: SEE NOTE	
TOLERANCE UNSPECIFIED .x 0.15 .xx 0.10 .xxx 0.05 Ang. 1°		DR: LIU MIAO CHK: SIMON APP: DAVID	DWG NO: A700 REV: A SCALE: 6:1 DATE: 2012.05.21